

Code No: 56029

Set No. 1

JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY HYDERABAD

III B.Tech. II Sem., II Mid-Term Examinations, April – 2014

VLSI DESIGN

Objective Exam

Name: _____ **Hall Ticket No.**

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Answer All Questions. All Questions Carry Equal Marks. Time: 20 Min. Marks: 10.

I Choose the correct alternative:

1. Good observability and controllability reduces number of test vectors required for_____ []
A. CMOS Testing B. manufacturing test C. Chip level Test D. built in self test
2. The limitation of serial/parallel multiplier is that _____ frequency is limited by the propagation through the array of adders. []
A. maximum B. minimum C. same D. none
3. Which of the following is not related in implementation of a logic/binary cell for storing one-bit []
A. 2 inputs and 1 output
B. data input
C. select input enables the cell for reading and writing.
D. read/write input determines the cell operation when it is selected.
4. Which of the following is a volatile type of memory []
A. DRAM B. SRAM C. Flash D. none
5. Which of the following are process technologies in CPLD []
A. EPROM, EEPROM and FLASH B. SRAM, ANTIFUSE & EEPROM
C. FLASH, SRAM and ANTIFUSE D. FLASH, SRAM & ANTIFUSE
6. In commercial FPGS chips, Look Up Tables usually have either 4 or 5 inputs which require _____ storage cells. []
A. 16 and 24 B. 16 and 32 C. 8 and 16 D. 12 and 24
7. A comparator is build with an _____ and an _____ []
A. adder, or B. adder, inverter C. and, inverter D. adder, and
8. Which of the following allows a larger no. of array elements to be utilized than a channeled array for the same size of die []
A. sea of gate arrays B. channel gate array
C. structured gate array D. none of the above
9. An embedded gate array or structured gate array is a combination of []
A. CBIC B. MGA C. both A and B D. none
10. Process of converting unoptimized Boolean description to a PLA format is known as []
A. translation B. flattening C. mapping D. factoring

Cont.....2

II Fill in the blanks

11. The _____ breaks the carry computation in to two steps starting with the computation of two intermediate values.
12. _____ is the process of optimizing Boolean equation at the logic level and mapping them to a techno-specific library of cells.
13. _____ is the process of splitting a single design among multiple devices.
14. JTAG stands for _____
15. _____ are used to control the output of the optimization and mapping process.
16. _____ is a degree to which it can be observed that node at output operates correctly.
17. _____ provides fixed interconnection of along with its four sides.
18. Fault coverage is defined as the percentage of fault that can be detected by the applied _____
19. A _____ is tested by shifting a special pattern through the scan path before stuck at faults begins.
20. _____ provides each wire a route through a set of areas and avoids wasting of chip area

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A. translation B. flattening C. mapping D. factoring
8. Good observability and controllability reduces number of test vectors required for _____ []
A. CMOS Testing B. manufacturing test C. Chip level Test D. built in self test
9. The limitation of serial/parallel multiplier is that _____ frequency is limited by the propagation through the array of adders. []
A. maximum B. minimum C. same D. none
10. Which of the following is not related in implementation of a logic/binary cell for storing one-bit []
A. 2 inputs and 1 output
B. data input
C. select input enables the cell for reading and writing.
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II Fill in the blanks

11. JTAG stands for _____
12. _____ are used to control the output of the optimization and mapping process.
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JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY HYDERABAD**III B.Tech. II Sem., II Mid-Term Examinations, April – 2014****VLSI DESIGN****Objective Exam**Name: _____ Hall Ticket No.

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Cont.....2

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19. JTAG stands for _____
20. _____ are used to control the output of the optimization and mapping process.

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Set No. 4

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